

30V N-Channel MOSFET

Product Summary

- V_{DS} 30V
- I_D 5.6A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) < 24mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) < 38mohm
- 100% ∇V_{DS} Tested

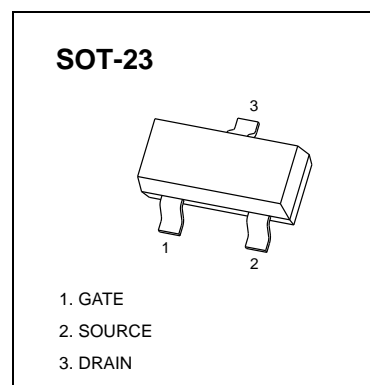
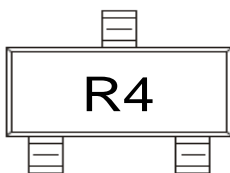
General Description

- Trench Power LV MOSFET technology
- High density cell design for low $R_{DS(ON)}$
- High Speed switching

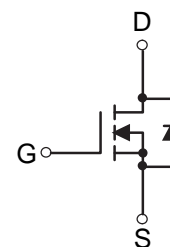
Applications

- Battery protection
- Load switch
- Power management

Marking: R4



Equivalent Circuit



■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ\text{C}$	I_D	5.6	A
	$T_A=70^\circ\text{C}$		4.5	
Pulsed Drain Current ^A		I_{DM}	30	A
Total Power Dissipation	$T_A=25^\circ\text{C}$	P_D	1.2	W
	$T_A=70^\circ\text{C}$		0.8	W
Thermal Resistance Junction-to-Ambient ^B		$R_{\theta JA}$	104	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range		T_J, T_{STG}	-55 ~ +150	$^\circ\text{C}$



FTK3404A

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS1}	V _{GS} =± 20V, V _{DS} =0V			± 100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1	1.5	2.2	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =5.6A		17	24	mΩ
		V _{GS} =4.5V, I _D =5A		26	38	
Diode Forward Voltage	V _{SD}	I _S =5.6A, V _{GS} =0V			1.2	V
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHZ		526		pF
Output Capacitance	C _{oss}			78		
Reverse Transfer Capacitance	C _{rss}			69		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =5.6A		12.22		nC
Gate-Source Charge	Q _{gs}			2.37		
Gate-Drain Charge	Q _{gd}			2.31		
Reverse Recovery Charge	Q _{rr}	I _F =5.6A, di/dt=100A/us		1.28		ns
Reverse Recovery Time	t _{rr}			16.5		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DS} =15V, I _D =5.6A R _{GEN} =3Ω		5		ns
Turn-on Rise Time	t _r			28.2		
Turn-off Delay Time	t _{D(off)}			12.8		
Turn-off fall Time	t _f			21.6		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



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Typical Performance Characteristics

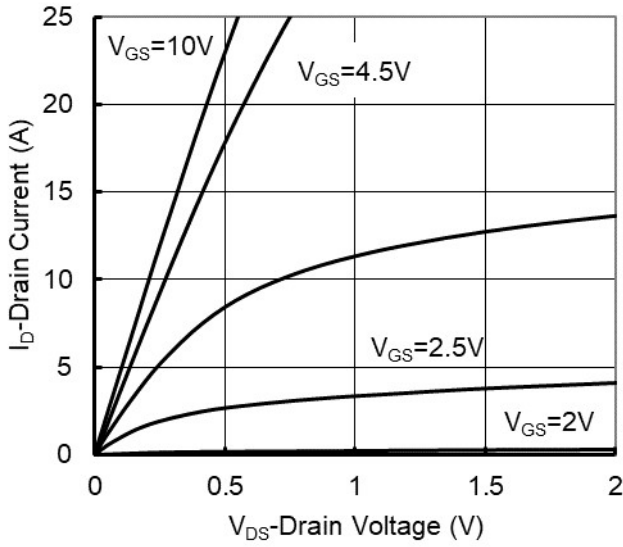


Figure 1. Output Characteristics

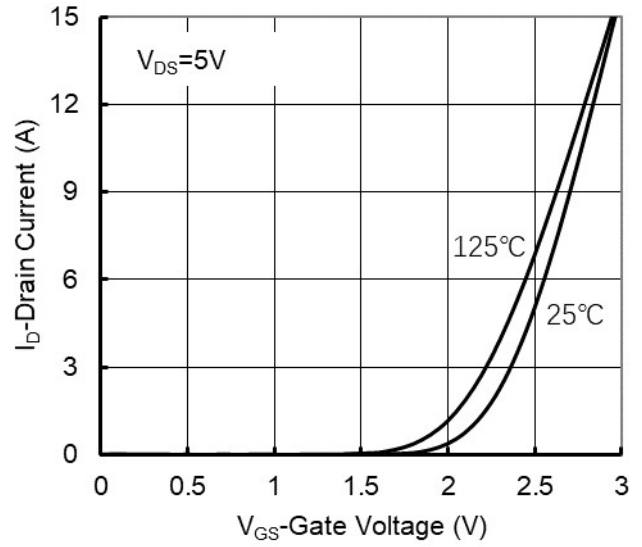


Figure 2. Transfer Characteristics

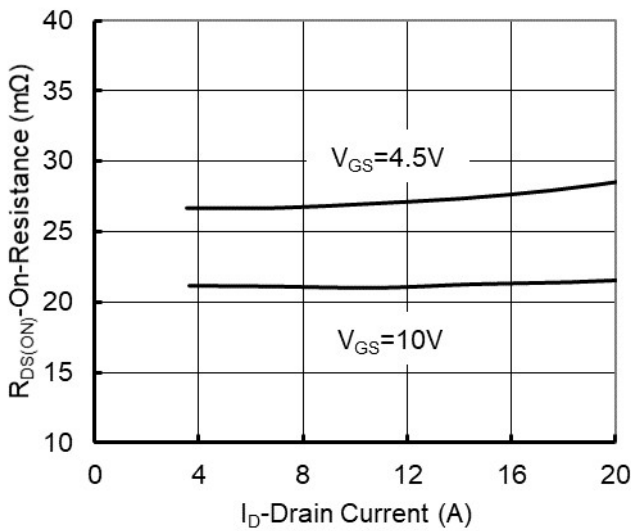


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

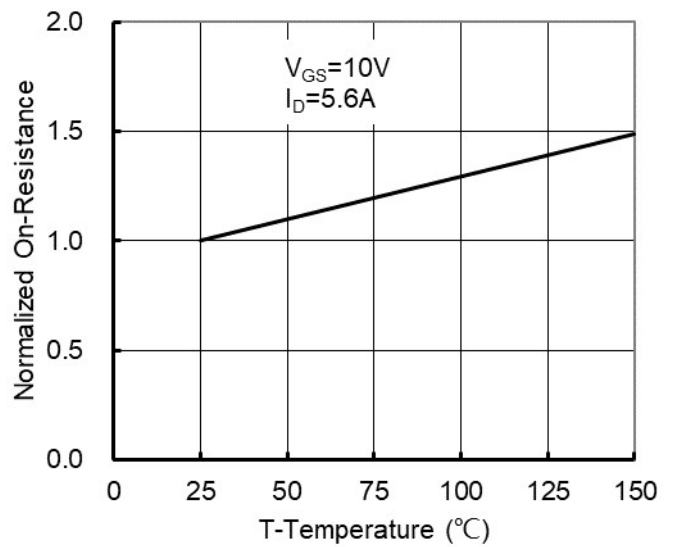


Figure 4: On-Resistance vs. Junction Temperature

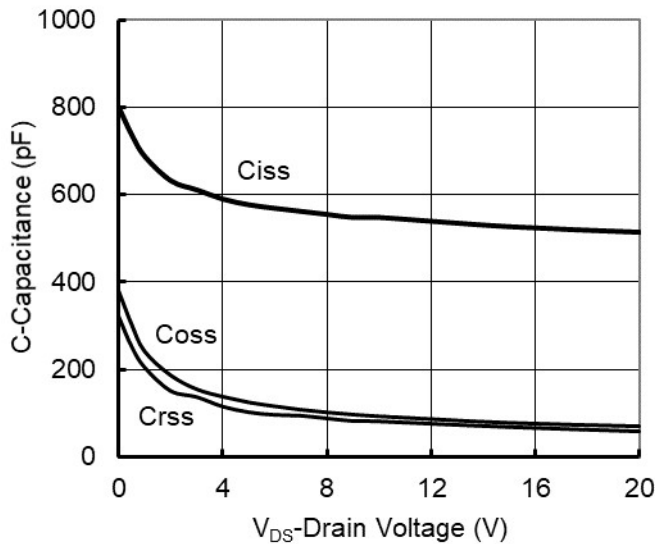


Figure 5. Capacitance Characteristics

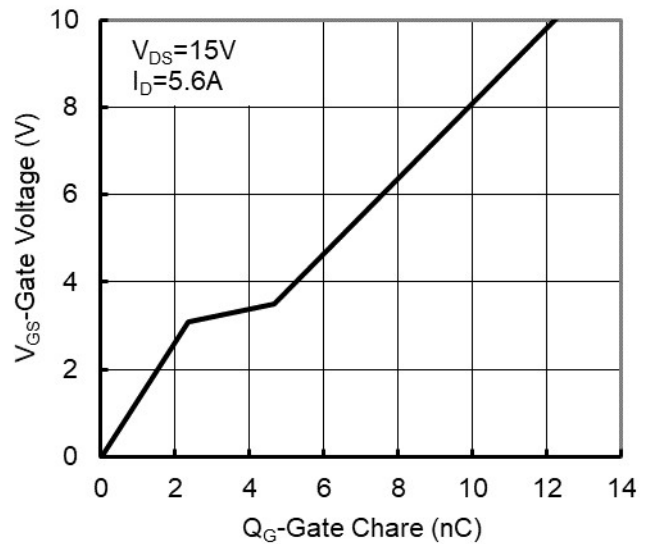


Figure 6. Gate Charge

■ Typical Performance Characteristics(Con.)

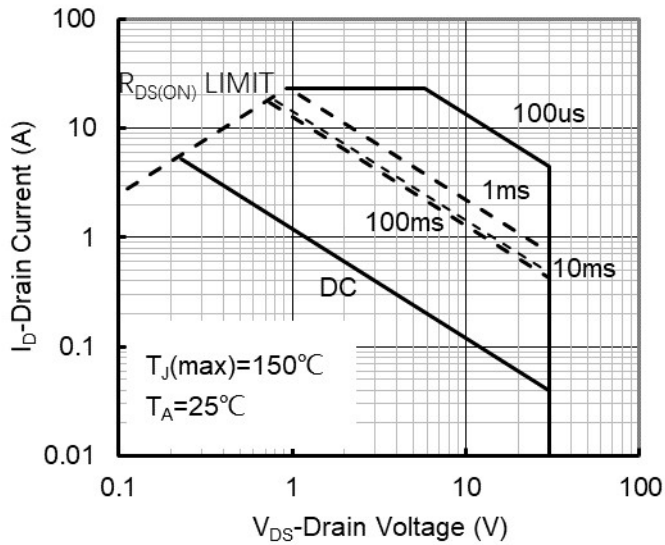


Figure7. Safe Operation Area

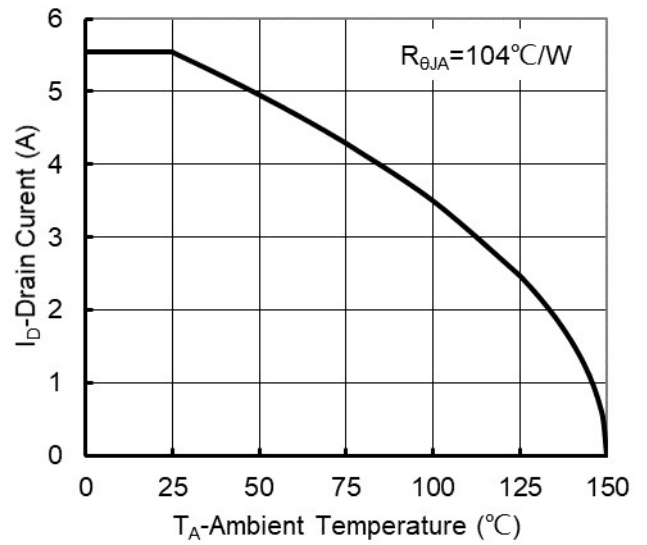


Figure8. Maximum Continuous Drain Current vs Ambient Temperature

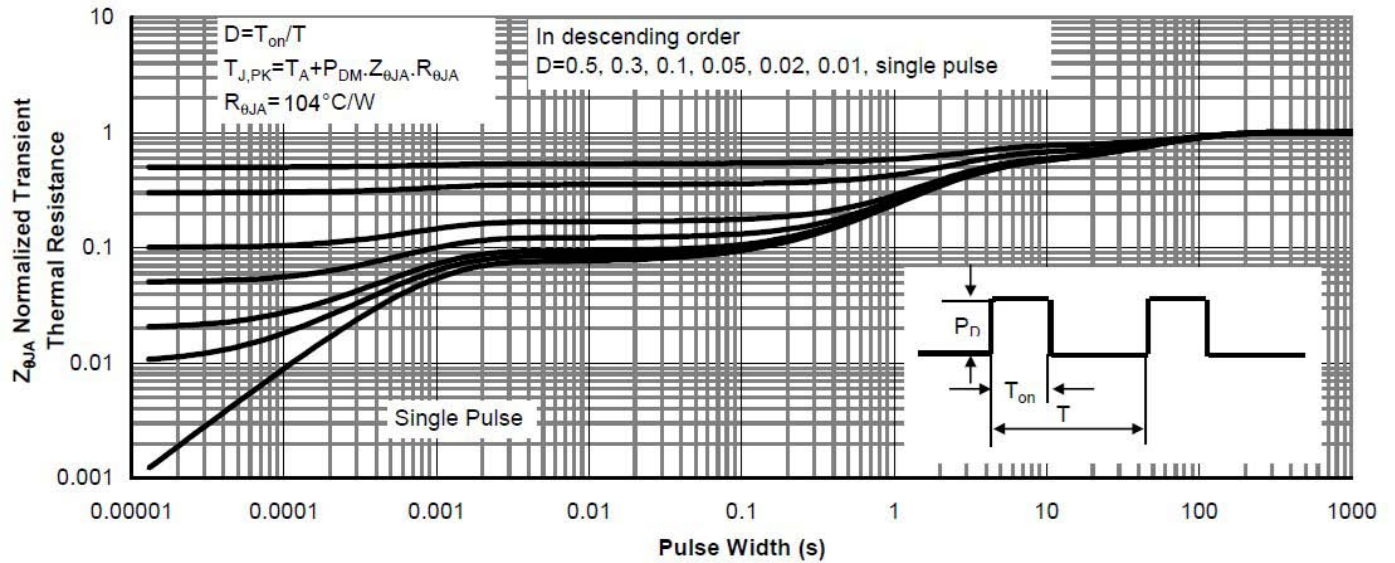
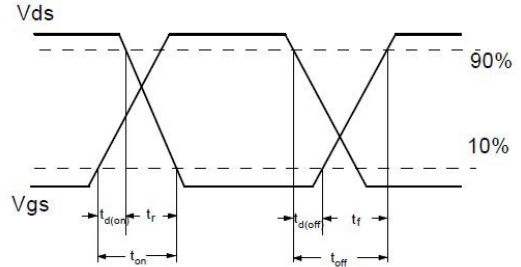
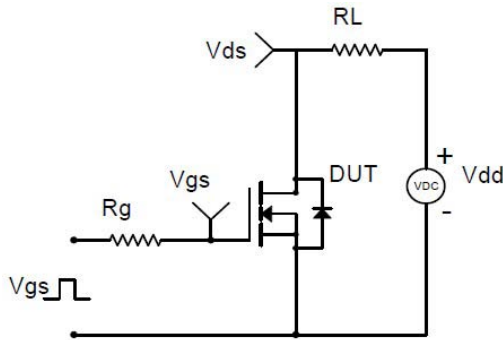
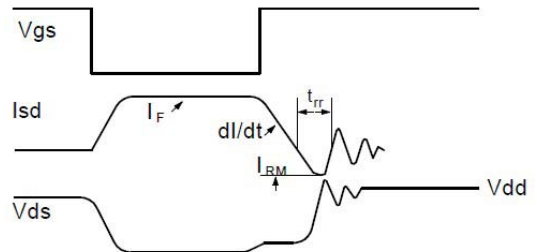
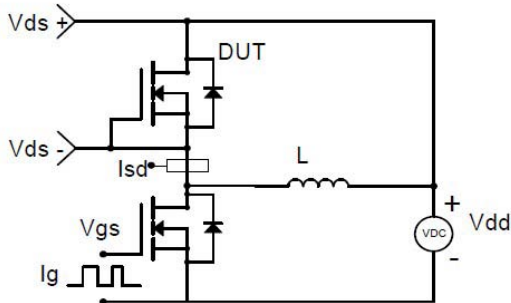


Figure9. Normalized Maximum Transient Thermal Impedance

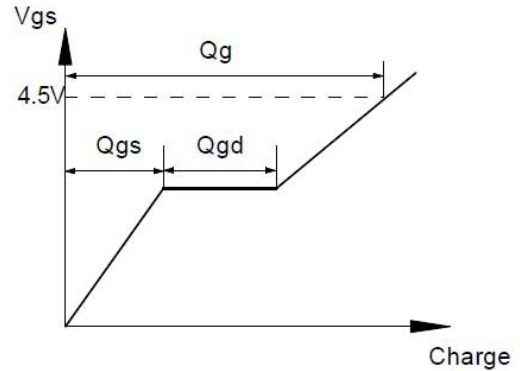
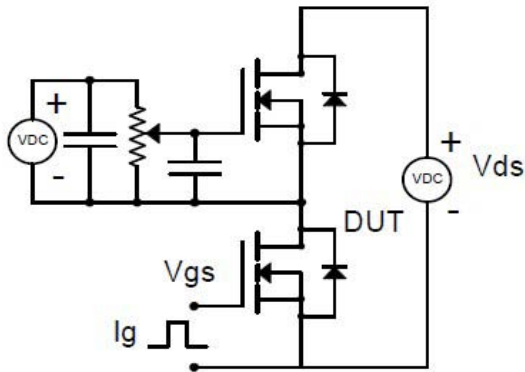
■ Test Circuits and Waveforms



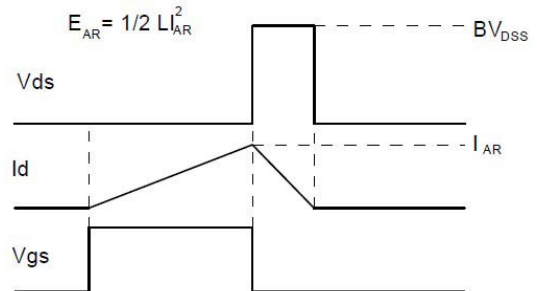
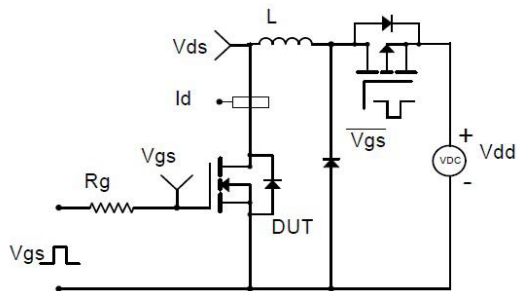
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

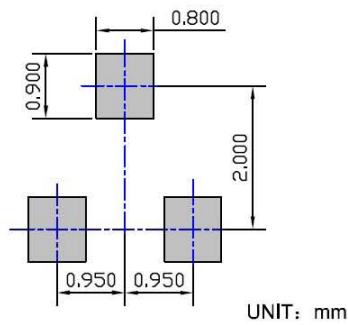
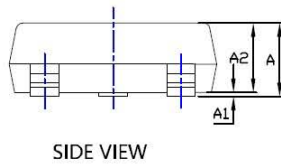
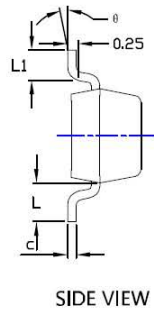
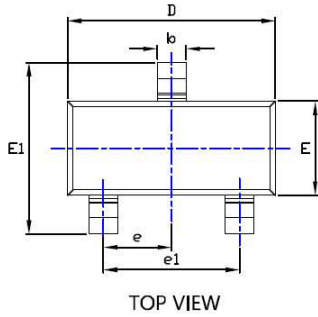


Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

■ SOT-23 Package information



SUGGESTED SOLDER PAD LAYOUT

SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.035	---	0.045	0.900	---	1.150
A1	0.000	---	0.004	0.000	---	0.100
A2	0.035	0.038	0.041	0.900	0.975	1.050
b	0.012	0.016	0.020	0.300	0.400	0.500
c	0.004	---	0.008	0.100	---	0.200
D	0.110	0.114	0.118	2.800	2.900	3.000
E	0.047	0.051	0.055	1.200	1.300	1.400
E1	0.089	0.094	0.100	2.250	2.400	2.550
e	0.037TYP			0.950TYP		
e1	0.071	0.075	0.079	1.800	1.900	2.000
L	0.022REF			0.550REF		
L1	0.012	0.016	0.200	0.300	0.400	0.500
θ	0°	---	8°	0°	---	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.